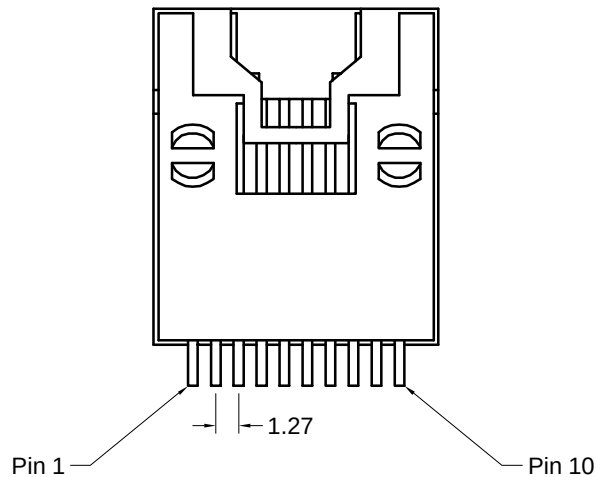
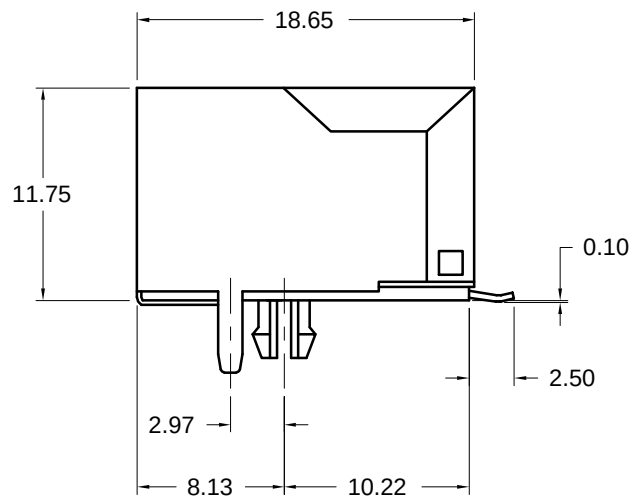
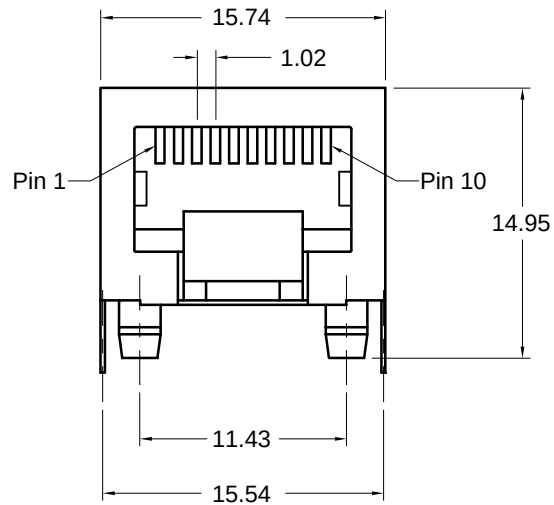
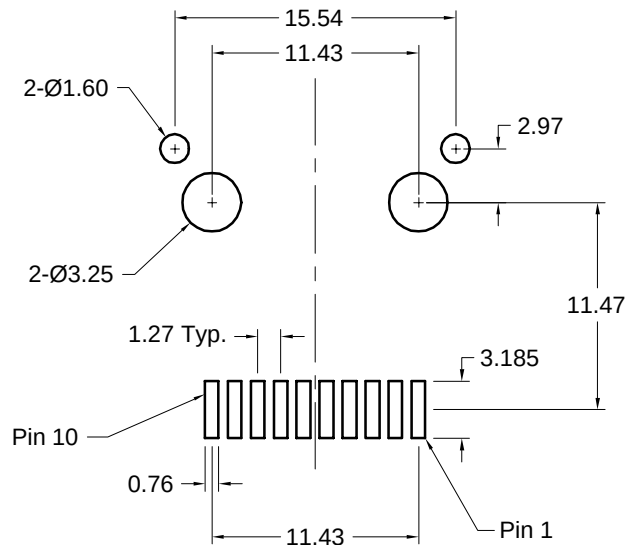




Recommended PCB Layout
(top view)



Part Number	Contact Area Plating Finish
GM-SMT2-S-1010	15u" Gold (standard)
GM-SMT2-S-1010-50	50u" Gold (50 option)

Materials and Finish

Housing Material:
high temp. thermoplastic,
(reflow process compatible)
UL 94V-0 rated, black color

Recommended Reflow Temperature:
230°C for 30 seconds,
260°C max.

Design meets UL 1863 Sec. 8
Electrical Probe and Sec. 20
Child Finger test requirements

Shield Material:
copper alloy, 0.20mm thick,
nickel plated 90u" min,

Contact Material: phosphor bronze

Contact Plating Options:
Standard: 0.0001" Nickel
Plating, Selective Plating
Gold Flash on Contact
Area, Tin/Lead on Termination End

50: 0.0001" Nickel Plating,
Selective Plating 0.000050"
Gold on Contact Area to
Comply with FCC Requirements
Under No. 47 C.F.R. Part 68,
Subpart F, Tin/Lead on
Termination End

Electrical Characteristics

Insulation Resistance:
500 Megohms min.

Dielectric Withstanding Voltage:
1000V rms, 60Hz

Contact Resistance:
20 milliohms max.

Current Rating: 1.5 Amps

Durability Rating:
1000 mating cycles min.

Operating Temperature:
-40°C to +85°C

CSA Certified File No. LR78160
UL Recognized File No. E134345

REVISION	DATE	DESCRIPTION	DRAWN BY	CHECKED BY	UNITS	GM-SMT2-S-1010	Right Angle Modular Jack, Shielded 10 position, 10 contacts, Surface Mount	
A4	3/20/02	ref ECD #01-199	C. Leiva		mm			
A5	6/4/02	ref ECD #02-038	REVISED BY	APPROVED BY	DATE			
B1	7/12/02	ref ECD #02-072	C. Leiva		9/23/97			

Mouser Electronics

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